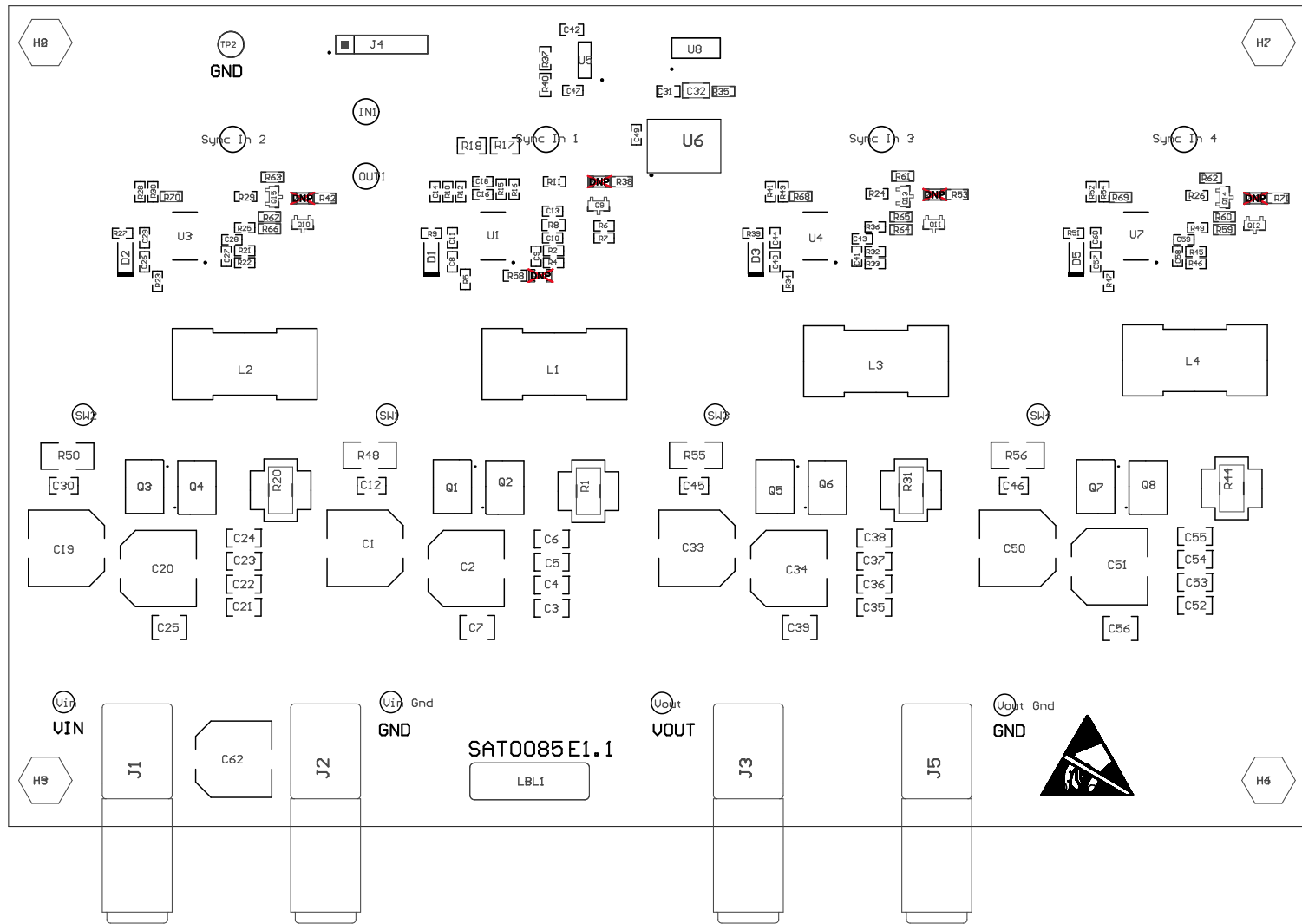


Z21 ■ Install label in silkscreened box per final wash. Text shall be per the Label Table in the PDF schematic.
 Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.
 Z25 ■ When installing J1, J2, J3, and J5, solder AND bolt them.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
IGNORE -> Top Overlay			
PLOT NAME = Top Assembly Drawing	GENERATED : 7/10/2014 2:48:04 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED, AND MAY NOT BE IN BILL OF MATERIALS
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: SAT0085	REV: E1.1	SUN REV: Not In VersionControl
	IGNORE -> Bottom Overlay		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/10/2014	2:48:04 PM	TEXAS INSTRUMENTS

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